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LIST OF ABBREVIATION

SEU Single Event Upset

TMR Triple Modular Redundancy

SOI Silicon On Insulator

SOS Silicon On Sapphire

TID Total Ionization Dose

SEE Single Event Effects

MTBF Mean Time Between Failure

FIT Failure In Time

ICAP Internal Configuration Access Port

LUT Look Up Table

MTTR Mean Time To Repair

MTBF Mean Time Between Failure